Power Inductor SMD Low Profile, High Current AEC-Q200

MERITEK

FEATURE

- Magnetic Shield Construction for Power Circuit.
- Large Current and Low DC Resistance
- Low profile power inductors
- Application: DC/DC Converter, Battery Powered Devices,
 Low Profile High Current Power Supply, Notebook/Server
- AEC-Q200 Compliant





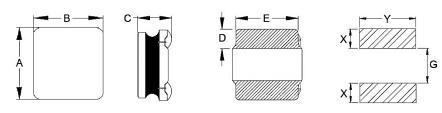
ELECTRICAL CHARACTERISTICS

Part Number	Inductance	Tolerance	Test Freq.	I _{RMS}	; (A)	I _{SAT}	(A)	DCR	(mΩ)
Fait Number	(µH)	(%)	(Hz)	Тур.	Max.	Тур.	Max.	Тур.	Max.
PIW06R47MBM63	0.47	±20	1V/1M	4.00	3.50	6.80	6.20	42	50.4
PIW06R68MBM63	0.68	±20	1V/1M	3.20	2.80	5.60	5.00	52	62.4
PIW061R0MBM63	1.00	±20	1V/1M	2.90	2.60	4.50	4.00	75	90.0
PIW061R5MBM63	1.50	±20	1V/1M	2.20	1.90	3.80	3.40	120	144
PIW062R2MBM63	2.20	±20	1V/1M	2.00	1.70	3.20	2.80	160	196
PIW063R3MBM63	3.30	±20	1V/1M	1.60	1.40	2.40	2.20	240	288
PIW064R7MBM63	4.70	±20	1V/1M	1.30	1.10	1.90	1.70	362	435
PIW06100MBM63	10.0	±20	1V/1M	0.90	0.70	1.30	1.10	800	960

Notes:

- All test data referenced to 25°C ambient.
- 2. Saturation Current (Isat) based on inductance drop (∆L/L0: ≦30%) approximately
- 3. Heat Rated Current (Irms) based on temperature rise (ΔT: 40 °C) approximately
- 4. Operating Temperature: -55°C $\sim +125$ °C (Including Self-temperature rise)

DIMENSIONS



								(Unit: mm)
Part Number	Α	В	C Max	D	E	X	Υ	G
PIW06-BM63	2.0 ±0.2	1.6 ±0.2	1.0	0.7 ±0.3	1.6 ±0.2	1.0	2.0	0.5

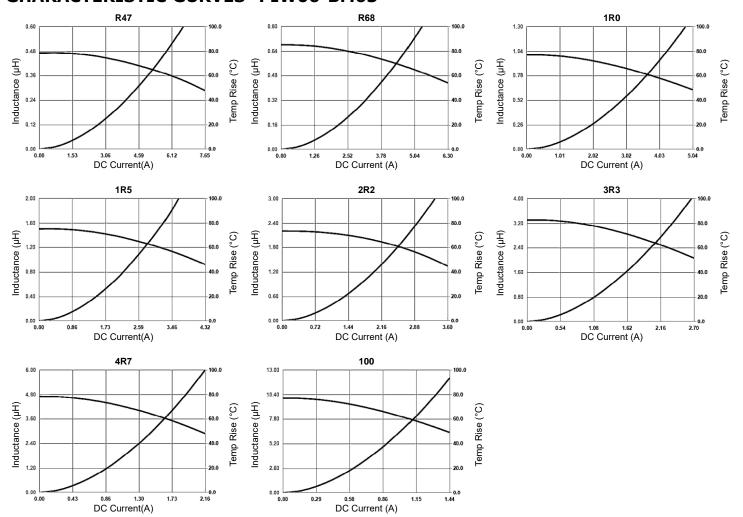
PART NUMBERING SYSTEM

 $\frac{\text{PIW}}{\text{(1)}}$ $\frac{06}{\text{(2)}}$ $\frac{100\text{M}}{\text{(3)}}$ $\frac{\text{B}}{\text{(4)}}$ $\frac{\text{M63}}{\text{(5)}}$

No	Item	Code	Description				
(1)	Product Code	PIW	Power Inductor Series, Wire Wound Type				
(2)	Size Code	06	0806, 2.0x1.6mm	LxW (mm)			
(3)	Inductance	100M	10μH ±20 (M)	R47: 0.47µH, 2R2: 2.2µH			
(4)	Internal Code	В	B: 1.0mm Height	A: 0.8mm, C: 1.2mm, D: 1.5mm			
(5)	Series Code	M63	Surface Mount Shielded, Low Profile, High Current series, AEC-Q200 Compliant				

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CHARACTERISTIC CURVES- PIW06-BM63



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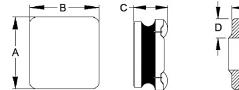


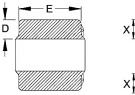
RELIABILITY TEST CONDITON AND REQUIREMENT

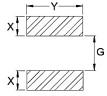
Item		Test Standar	ds / Condition	s / Equipment		Requirement
Inductance	HP4284A, CH	11025, CH3302	2, CH1320, CH	1320S, LCR M	eter	Refer to specification
DC Resistance		ent33420A Mic				Refer to specification
Mechanical Shock	Type SMD Lead 3 shocks in ea	Peak value (g's) 100 100 ch direction alc	Normal duration (D) (ms) 6 6 6 ng 3 perpendio	Wave form Half-sine Half-sine cular axes (18 s	Velocity change (Vi) ft/sec 12.3 12.3 shocks).	Appearance: No damage Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value
Solderability	Test Time: 5 + Method D cate	Hrs at 155°C di 0/-0.5 seconds. egory 3. (steam -0/-0.5 seconds	aging 8 hours:		°C±5°C	More than 95% of the terminal electrode should be covered with solder.
Resistance to Soldering Heat	Temperature range Completely co	ature: 260±5°C amp/immersion ver the termina cles: 1 heat cycl	and emersion tion.		6 mm/s.	Appearance: No damage Inductance: within ±10% of initial value Q: Shall not exceed the specification value
Vibration	Equipment : V Total Amplitud	quency: $10\sim21$ (ibration checke e:1.52mm ± 10° 12 hours (20 m	er %		entations)	RDC: within ±15% of initial value and shall not exceed the specification value
High Temperature Exposure	Temperature: Duration 1000 Measured at re		re after placing	for 24±2hrs		Appearance: No damage
Biased Humidity	Duration: 1000	3% R.H. Tempe)Hrs Min Room Temperat		Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall		
High Temperature Operational Life		125±2°C)Hrs Min. with 1 Room Temperat				not exceed the specification value
Temperature Cycling	Condition for 1 Step Temperature Duration Number of Cyd Measured at re	1 -55 ±2°C 30min Min	2 125 ±2°C 1 min Max	3 125 ±2°C 30 min Min for 24±2hrs	4 Low Temp 1 min Max	Appearance: No damage Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value
Thermal Shock	Condition for 1 Step Temperature Duration Number of cyc Measured at re	1 -55 ±2°C 15±1min	20	2 5 ±2°C Osec for 24±2 hrs.	3 125 ±2°C 15±1min	Appearance: No damage Inductance: within ±10% of initial value Q: Shall not exceed the specification value RDC: within ±15% of initial value and shall not exceed the specification value
ESD	AEC-Q200-00	2 HBM ESD, C	ontact Dischar	ge Level: 4KV (Level 2)	Appearance: No damage
Resistance to Solvents	Add aqueous	wash chemical	- OKEM clean	or equivalent.		Appearance : No damage
Terminal Strength	Component mounted on a PCB apply a force 1.8kg to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested.					Appearance : No damage
Board Flex	Place the 100x40mm FR4 board into a fixture with the component facing down. Apply a force which will bend the board (D) x = 2mm minimum. Duration: 60 (+5) seconds. The Force is to be applied only once to the board					Appearance : No damage
Flammability	Electrical Test	not Required				V-0 or V-1 are acceptable.

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DIMENSIONS







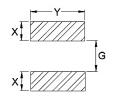
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Part Number	Α	В	C Max	D	E	Х	Y	G
PIW06-BM63	2.0 ±0.2	1.6 ±0.2	1.0	0.7 ±0.3	1.6 ±0.2	1.0	2.0	0.5
PIW06-CM63	2.0 ±0.2	1.6 ±0.2	1.2	0.7 ±0.3	1.6 ±0.2	1.0	2.0	0.5
PIW08-BM63	2.5 ±0.2	2.0 ±0.2	1.0	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7
PIW08-CM63	2.5 ±0.2	2.0 ±0.2	1.2	0.9 ±0.3	2.0 ±0.2	1.15	2.5	0.7

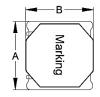


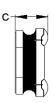


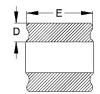


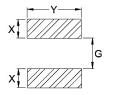


								(Unit: mm)
Part Number	Α	В	C Max	D	E	Х	Υ	G
PIW-30CM63	3.0±0.2	3.0±0.2	1.2	0.9 ±0.3	2.7 ±0.3	1.3	3.5	0.9
PIW-30DM63	3.0±0.2	3.0±0.2	1.5	0.9 ±0.3	2.7 ±0.3	1.3	3.5	0.9









(Unit: mm)

Part Number	Α	В	C Max	D	E	X	Υ	G
PIW-40EM63	4.0±0.2	4.0±0.2	2.0	1.1 ±0.3	3.5 ±0.3	1.5	4.5	1.5

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RECOMMENDED SOLDERING PROFILES

	Reflow Condition							
_	Temp. Min T _{s(min)}	150°C						
Pre Heat	Temp. Max T _{s(max)}	200°C						
11001	Time (min. to max.) (t _s)	60 ~120 seconds						
	ramp up rate (Liquidus ture) (T∟) to peak	3°C/second max						
T _{S(max)} to	T _∟ (Ramp-up rate)	3°C/second max						
Reflow	Temp. (T _L)	217°C						
Reliow	Time (min. to max.) (t _L)	60 ~150 seconds						
Peak Ten	nperature (T _P)	See table below						
Time with	nin 5°C of actual peak ture (t _p)	10 seconds max						
Ramp-do	wn Rate	6°C/second max						
Reflow T	imes	3 times max						

Peak Temperature (T _P)								
Volume < 350mm ³ 350-2000mm ³ > 2000m								
Thickness < 1.6mm	260°C	260°C	260°C					
Thickness 1.6-2.5mm	260°C	250°C	245°C					
Thickness ≥ 2.5mm	250°C	245°C	245°C					

^{*}Specifications subject to change without notice

